

NOT RECOMMENDED FOR NEW DESIGN USE DMP3125L



DMG2307L

P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
	90mΩ @ V _{GS} = -10V	-3.8A
-30V	134mΩ @ V _{GS} = -4.5V	-3.1A

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

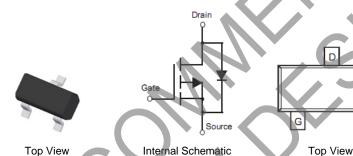
- General Purpose Interfacing Switch
- Power Management Functions
- Load Switch for Portable Devices

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208e3
- Weight: 0.08 grams (Approximate)



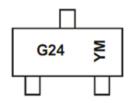
Ordering Information (Note 4)

Part Number	Case	Packaging
DMG2307L-7	SOT23	3,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



 $G24 = Product Type Marking Code \\ YM = Date Code Marking \\ Y or \overline{Y} = Year (ex: F = 2018) \\ M = Month (ex: 9 = September)$

Date Code Key

Year	2018	2019	2020	2021	202	2 20	23	2024	2025	2026	2027	2028
Code	F	G	Н		J		<	L	М	N	0	Р
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code						_	-				N.I.	7

DMG2307L Document number: DS35415 Rev. 5 - 3



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Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage			V_{DSS}	-30	V
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current (Note 5) V _{GS} = -10V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	-2.5 -2.0	Α
Continuous Drain Current (Note 6) V _{GS} = -10V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	-3.8 -3.0	Α
Continuous Drain Current (Note 6) V _{GS} = -10V	t ≦10sec	$T_A = +25$ °C $T_A = +70$ °C	I _D	-4.6 -3.6	Α
Continuous Drain Current (Note 6) V _{GS} = -4.5V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	-3.1 -2.5	Α
Pulsed Drain Current (Note 6)	I _{DM}	-20	А		

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	Po	0.76	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	159	°C/W
Total Power Dissipation (Note 6)	PD	1.36	W
Thermal Resistance, Junction to Ambient (Note 6)	Reja	94	°C/W
Total Power Dissipation (Note 6) t ≤ 10sec	P_{D}	1.9	W
Thermal Resistance, Junction to Ambient (Note 6) t ≤ 10sec	Reja	65.8	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)		1 11				
Drain-Source Breakdown Voltage	BV _{DSS}	-30	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current @T _C = +25°	°C I _{DSS}	-	_	-1.0	μΑ	$V_{DS} = -30V, V_{GS} = 0V$
Gate-Source Leakage	Igss	-	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-1.0	_	-3.0	٧	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance		_	70	90	mΩ	$V_{GS} = -10V, I_D = -2.5A$
Static Dialii-Source Off-Resistance	R _{DS(ON)}	_	105	134	11122	$V_{GS} = -4.5V, I_D = -2.5A$
Forward Transfer Admittance	Y _{fs}	_	4.8		S	$V_{DS} = -10V, I_{D} = -2.5A$
Diode Forward Voltage (Note 6)	V_{SD}	_	-0.75	-1.0	V	$V_{GS} = 0V, I_{S} = -1A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	_	371.3	—	рF	151/1/ 01/
Output Capacitance	Coss	_	51.3	_	рF	$V_{DS} = -15V, V_{GS} = 0V,$ -f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	45.9		рF	1 = 1.01/11 12
Gate Resistance	R_{g}	_	17	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	4.0		nC	
Total Gate Charge (V _{GS} = -10V)	Q_g	_	8.2		nC	$V_{GS} = -10V, V_{DS} = -15V,$
Gate-Source Charge	Qgs	_	0.9	_	nC	$I_D = -3A$
Gate-Drain Charge	Q_{gd}	_	1.2		nC	
Turn-On Delay Time	t _{D(ON)}	_	4.8	_	ns	V 45V V 40V
Turn-On Rise Time	t _R	_	7.3	_	ns	$V_{DS} = -15V, V_{GS} = -10V,$
Turn-Off Delay Time	t _{D(OFF)}	_	22.4	_	ns	$R_L = 15\Omega$, $R_G = 6\Omega$, $R_D = -1A$
Turn-Off Fall Time	t _F	_	13.4	_	ns	ID = -IA

Notes:

5. Device mounted on FR-4 PCB, with minimum recommended pad layout.6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.

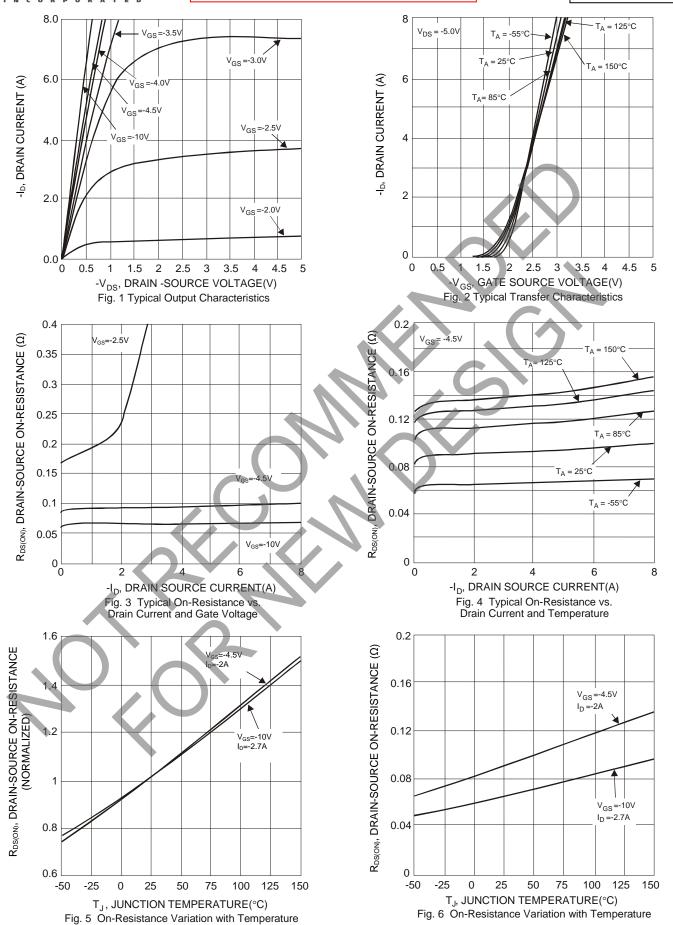
7. Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to product testing.



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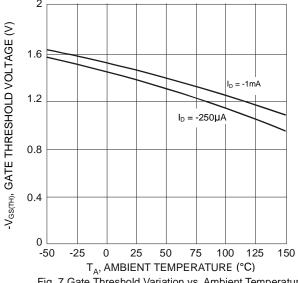
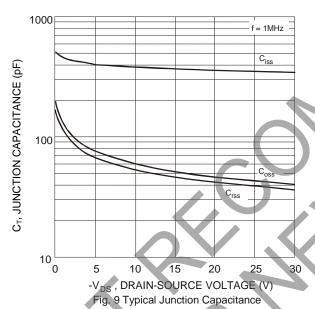
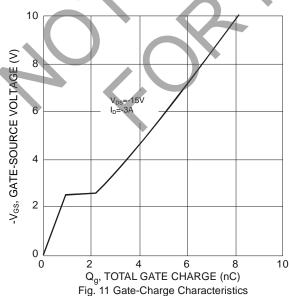
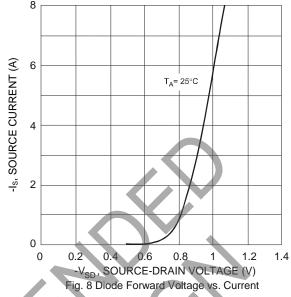


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







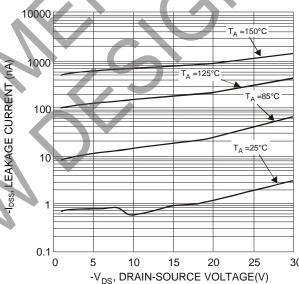


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage

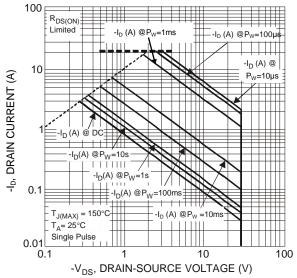
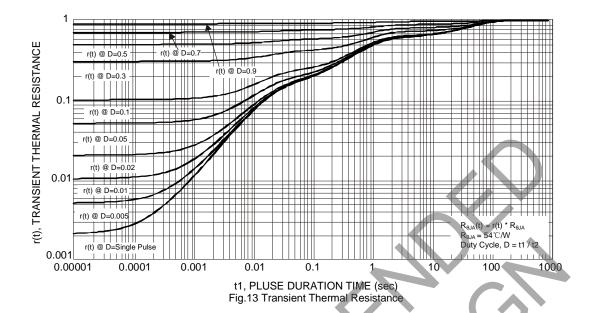


Fig. 12 SOA, Safe Operation Area



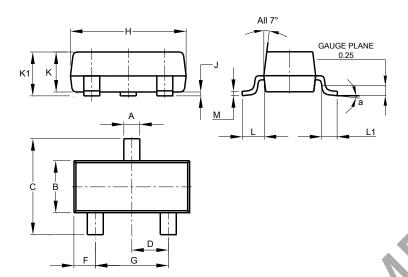




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23

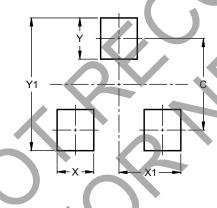


SOT23								
Dim	Min	Max	Тур					
Α	0.37	0.51	0.40					
В	1.20	1.40	1.30					
С	2.30	2.50	2.40					
D	0.89	1.03	0.915					
F	0.45	0.60	0.535					
G	1.78	2.05	1.83					
H	2.80	3.00	2.90					
7	0.013	0.10	0.05					
K	0.890	1.00	0.975					
K1	0.903	1.10	1.025					
L	0.45	0.61	0.55					
L1	0.25	0.55	0.40					
M	0.085	0.150	0.110					
а	0°	8°						
All	All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23



Dimensions	Value (in mm)
С	2.0
Х	8.0
X1	1.35
Υ	0.9
Y1	2.0



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